

FOR IMMEDIATE RELEASE

YINCAE Launches Innovative UF 88UV Optical Underfill — Customers' Best Choice After Competitive Evaluation

(Albany, NY) 08/10/2026 — YINCAE Advanced Materials, LLC announces the launch of **UF 88UV**, an innovative high-transparency optical underfill designed for optical modules, optoelectronic devices, and advanced semiconductor packaging.

UF 88UV delivers approximately 100% visible-light transmittance, providing exceptional optical clarity for applications where maintaining a highly transparent optical path is critical. In competitive evaluations, customers selected UF 88UV over competing underfill solutions for demanding optical module applications.

Beyond its outstanding optical performance, UF 88UV offers excellent processability. The material flows readily at room temperature into small gaps, supporting efficient underfill processing without the need for elevated-temperature dispensing. After cure, UF 88UV exhibits fluorescence, enabling easy inspection and verification of underfill coverage.

UF 88UV also demonstrates outstanding reliability. After Pressure Cooker Testing (PCT) followed by five 260°C reflow cycles, the material exhibited no observable change in optical properties and no delamination.

Key Benefits of UF 88UV

- Approximately 100% visible-light transmittance
- Selected by customers over competing underfill solutions
- Room-temperature flow into small gaps for easy processing
- Fluorescent after cure for easy inspection
- No observable change in optical properties after PCT and 5× 260°C reflow
- No delamination after reliability testing
- Designed for optical modules, optical sensors, imaging devices, optoelectronic components, and advanced semiconductor packaging

UF 88UV is now available for customer evaluation and qualification. For more information, visit www.yincae.com or contact info@yincae.com.

About YINCAE



YINCAE Advanced Materials, LLC
93 Broadway
Menands, NY 12204
T (518) 452-2880
F (518) 452-2779

YINCAE Advanced Materials develops high-performance materials for semiconductor packaging, microelectronics, optoelectronics, and advanced manufacturing. Its portfolio of underfills, die attach materials, thermal interface materials and solder joint encapsulant supports innovations in AI, data centers, telecommunications, silicon photonics, quantum technologies, automotive electronics, and other high-growth markets.